

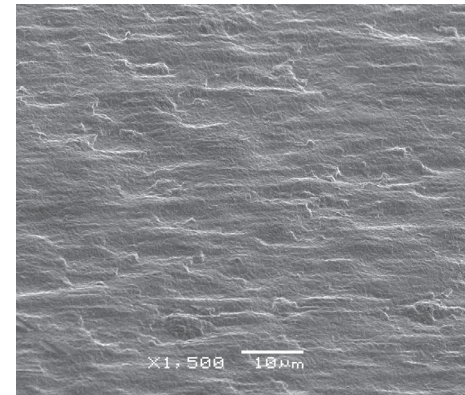
High reliability electrodeposited copper foil.

Applications:

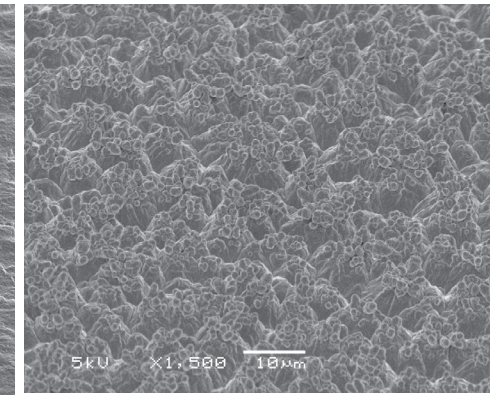
- PCB outer layers
- PCB inner layers

Features:

- IPC Grade III
- Treatment on matte side of foil
- Excellent adhesion to a wide range of resin systems



Untreated Drum Side
H oz. /18 μm (1500x)



Treated Matte Side
H oz. /18 μm (1500x)

Typical Values:

Attribute		Unit	Value						Reference
Thickness Designation			Q	T	H	1	2	3	IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12
Nominal Thickness		μm	9	12	18	35	70	103	
		oz.	1/4	3/8	1/2	1	2	3	
Area Weight		g/m ²	75.9	106.8	152.5	305	610	915	
		g/254 in ²	12.5	17.5	25	50	100	150	
		oz./ft ²	0.25	0.375	0.5	1	2	3	
Roughness	Drum Side Ra	μm	0.25						IPC-TM-650-2.2.17
		μ"	10						
	Matte Side Rz	μm	4.3	5.1	5.1	6.4	10.2	15.6	
		μ"	170	200	200	250	400	615	
Tensile	Ambient	Kg/mm ²	44.4	42.2	42.2	38.7	36.9	34.7	IPC-TM-650-2.4.18
		Kpsi	63	60	60	55	53	49	
	180°C	Kg/mm ²	21						
		Kpsi	30						
Elongation	Ambient	%	4	6	8	15	20	25.2	
	180°C	%	8						7.4
Peel Strength* (Matte/Treated Side)	Cond. B	Kg/cm	1.0	1.3	1.3	1.9	2.7	4.0	IPC-TM-650-2.4.8
		Lbs/in	5.6	7.0	7.5	10.5	15.0	22.5	

* Peel strength measured on 170°C Tg Epoxy

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